

Abstract

According to the invention, the distribution of material amounts deposited on the substrate may be optimized for magnetron sputter coating in which a magnetron magnetic field pattern (9) is cyclically (M_y) moved along the sputtering surface (7) and a substrate (11) is passed along the sputter surface (7), whereby the sputter rate is modulated by means of a modulation device (3), phase-locked with the cyclical movement (M_7) of the field pattern (9).